

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-5. (Canceled)

6. (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface including at least one unit each having a plurality of semiconductor element mount regions defined thereon;

a mask disposed on the second planar surface and having respective patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, said mask comprising a conductive film, and
guide holes into which guide pins are inserted,

wherein each unit includes a plurality of first pads defined by the respective patterns in the unit and a plurality of die pads defined by the respective semiconductor element mount regions in the unit

~~The sheet-like board member as defined in claim 10,~~ wherein the conductive film is disposed in the semiconductor element mount regions to form a the die pads.

7. (Canceled)

8. (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface including at least one unit each having a plurality of semiconductor element mount regions defined thereon;

a mask disposed on the second planar surface and having respective patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, said mask comprising a conductive film, and

guide holes into which guide pins are inserted,

wherein each unit includes a plurality of first pads defined by the respective patterns in the unit and a plurality of die pads defined by the respective semiconductor element mount regions in the unit,

wherein the conductive film is disposed on the second planar surface to form the die pads and/or outer lead electrode,

~~The sheet-like board member as defined in claim 7,~~ wherein a passive element to be placed on the die pad comprises a chip resistor or a chip capacitor.

9-15. (Canceled)

16. (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first planar surface, the second surface including at least one unit each of which includes protuberances and semiconductor mount regions formed on said second planar surface; and

guide holes into which guide pins are inserted,

wherein the protuberances define a plurality of first pads in or in the vicinity of the semiconductor element mount regions defined on the second planar surface , and

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit,

~~The sheet-like board member as defined in claim 12,~~ wherein the protuberances comprise[[s]] the die pads provided in the semi-conductor element mount region.

17. (Canceled)

18 (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first planar surface, the second surface including at least one unit each of which includes protuberances and semiconductor mount regions formed on said second planar surface; and

guide holes into which guide pins are inserted,

wherein the protuberances define a plurality of first pads in or in the vicinity of the semiconductor element mount regions defined on the second planar surface, and

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit

wherein the protuberances comprise the die pads and/or outer lead electrodes,

~~The sheet-like board member as defined in claim 17,~~ wherein a passive element is disposed on the die pad comprises a chip resistor or chip capacitor.

19-37. (Canceled)

38. (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface having at least one unit each of which has semiconductor element mount regions defined thereon;

a mask for etching disposed on the second planar surface and having patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, wherein each unit comprises a plurality of the patterns, and

guide holes into which guide pins are inserted,

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit,

wherein the mask comprises a conductive film

~~The sheet-like board member as defined in claim 33,~~ wherein the conductive coating film is disposed in the semiconductor element mount region to form a die pad.

39. (Canceled)

40. (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface having at least one unit each of which has semiconductor element mount regions defined thereon;

a mask for etching disposed on the second planar surface and having patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, wherein each unit comprises a plurality of the patterns, and guide holes into which guide pins are inserted,

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit,

wherein the mask comprises a conductive film,

wherein the conductive film is disposed on the second planar surface to form a die pad and/or outer lead electrode,

~~The sheet-like board member as defined in claim 39,~~ wherein a passive element is on the die pad comprises a chip resistor or a chip capacitor.

41-44. (Canceled)

45. (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface including at least one unit each having a plurality of semiconductor element mount regions defined thereon;

a mask disposed on the second planar surface and having respective patterns
corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor
element mount regions, said mask comprising a conductive film, and
guide holes into which guide pins are inserted,

wherein each unit includes a plurality of first pads defined by the respective patterns in
the unit and a plurality of die pads defined by the respective semiconductor element mount
regions in the unit,

~~The sheet-like board member as defined in claim 10~~ wherein a positioning mark is provided on
the sheet-like board member.

46. (Previously presented) The sheet-like board member as defined in claim 45 wherein
the positioning mark is formed by partially etching the sheet-like board member.

47-48. (Canceled)

49. (Currently Amended) A sheet-like board member comprising:
a first planar surface;
a second planar surface disposed opposite to the first planer surface, the second surface
including at least one unit each of which includes protuberances and semiconductor mount
regions formed on said second planar surface; and
guide holes into which guide pins are inserted,
wherein the protuberances define a plurality of first pads in or in the vicinity of the
semiconductor element mount regions defined on the second planar surface , and
wherein each unit includes a plurality of die pads defined by the respective
semiconductor mount regions in the unit,

~~The sheet-like board member as defined in claim 12~~ wherein a positioning mark is provided on
the sheet-like board member.

50. (Previously presented) The sheet-like board member as defined in claim 49 wherein
the positioning mark is formed by partially etching the sheet-like board member.

51-53. (Canceled)

54. (Currently Amended) A sheet-like board member comprising:
a planar surface defining at least one unit;
a sheet-like front side of predetermined thickness which is provided on the planar
surface;
a plurality of first pads formed in each unit in or in the vicinity of semiconductor element
mount regions defined in each unit on the planar surface;
protuberances in each unit formed on said planar surface and including wirings integrally
formed with the first pads, said plurality of first pads and said protuberances formed within an
abutting region defined on said planar surface, said abutting region provided to contact with an
upper metal mold; and
guide holes into which guide pins are inserted
wherein each unit includes a plurality of die pads defined by the respective
semiconductor mount regions in the unit,
~~The sheet-like board member as defined in claim 26 wherein a positioning mark is provided on~~
~~the sheet-like board member.~~

55. (Previously presented) The sheet-like board member as defined in claim 54 wherein the positioning mark is formed by partially etching the sheet-like board member.

56. (Canceled)

57. (Canceled)

58. (Currently Amended) A sheet-like board member comprising:
a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface having at least one unit each of which has semiconductor element mount regions defined thereon;

a mask for etching disposed on the second planar surface and having patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, wherein each unit comprises a plurality of the patterns, and guide holes into which guide pins are inserted,

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit,

~~The sheet-like board member as defined in claim 33~~ wherein a positioning mark is provided on the sheet-like board member.

59. (Currently Amended) A sheet-like board member comprising:

a first planar surface;

a second planar surface disposed opposite to the first surface, said second planar surface having at least one unit each of which has semiconductor element mount regions defined thereon;

a mask for etching disposed on the second planar surface and having patterns corresponding to a plurality of first pads formed in or in the vicinity of the semiconductor element mount regions, wherein each unit comprises a plurality of the patterns, and guide holes into which guide pins are inserted,

wherein each unit includes a plurality of die pads defined by the respective semiconductor mount regions in the unit,

wherein a positioning mark is provided on the sheet-like board member,

~~The sheet-like board member as defined in claim 58~~ wherein the positioning mark is formed by partially etching the sheet-like board member.

60. (Canceled)

61. (Canceled)

62. (Currently Amended) A method of manufacturing a semiconductor device comprising:

preparing a sheet-like board member as defined in claim 6;
partially etching the second planar surface of the sheet-like member so as to form the first pads;

disposing a circuit element onto a portion on the sheet-like board member;
molding a surface of the sheet-like board member by an insulating resin so that the sheet-like board member is covered,

~~The method of manufacturing a semiconductor device according to claim 61~~ wherein the sheet-like board member is fixed by means of vacuum suction.

63. (Canceled)

64. (Currently Amended) A method of manufacturing a semiconductor device comprising:

preparing a sheet-like board member as defined in any one of claims 16 and 54;
disposing a circuit element onto a portion of the protuberances of the sheet-like board member;

molding a surface of the sheet-like board member by an insulating plastic so that the sheet-like board member is covered,

~~The method of manufacturing a semiconductor device according to claim 63~~ wherein the sheet-like board member is fixed by means of vacuum suction.

65-75. (Canceled)